

REMARKS

Claims 12-16 are pending in the Application. Claims 12-16 have been amended. Claims 1-11 and 17-27 were previously cancelled. Reconsideration of all outstanding rejections in light of the following remarks is respectfully requested.

Amended claim 12 recites, *inter alia*, "a semiconductor structure comprising a substrate having an upper surface and a lower surface, one of said upper surface and said lower surface including at least one groove capable of being broken to separate the substrate into a plurality of segments."

The drawings stand objected to for not showing every feature of the claimed invention. In view of the amendment to claim 12, Applicant submits that the original filed drawings show every feature recited in the claims.

Claims 12-16 were rejected under 35 U.S.C. 112, first paragraph, for lack of support for "edge including a first cut portion and second broken portions comprising a sheared portion." Office Action at page 2. In view of amended claim 12, Applicant respectfully submits that the rejection under 35 U.S.C. 112, first paragraph be withdrawn.

Claims 12 and 13 stand rejected under 35 U.S.C. 102(b) as being anticipated by Yamaoka (JP 10-064854) (hereinafter Yamaoka).

Yamaoka discloses a substrate (54) having an upper surface and a lower surface (e.g., Figure 7). Yamaoka does not disclose *inter alia*, "a semiconductor structure comprising a substrate having an upper surface and a lower surface, one of said upper surface and said lower surface including at least one groove capable of being broken to separate the substrate into a plurality of segments," as claimed. Claims 13-16 depend from amended claim 12, and thus are allowable along with claim 12, for at least the reasons set forth above. Because Yamaoka fails to disclose every limitation of the

claimed invention, Applicants respectfully request withdrawal of the rejection.

Claim 14 stands rejected under 35 U.S.C. § 103(a) as being unpatentable over Yamaoka in view of Nishino et al. (U.S. Patent No. 6,010,384)(hereinafter Nishino). The Office Action states on page 4 that Yamaoka does not teach wherein said cut portion further comprises a scribed portion.

Nishino teaches a liquid crystal display device and method for manufacturing the same (e.g., Col. 1, lines 1-10). Nishino does not teach or suggest "a semiconductor structure comprising a substrate having an upper surface and a lower surface, one of said upper surface and said lower surface including at least one groove capable of being broken to separate the substrate into a plurality of segments," as claimed. Because neither Yamaoka or Nishino, taken alone or in combination, teach or suggest the claimed invention, Applicants respectfully request withdrawal of the rejection.

Claim 15 stands rejected under 35 U.S.C. § 103(a) as being unpatentable over Yamaoka in view of Yamada et al. (U.S. Patent Application Publication No. 2001/0005599) (hereinafter Yamada). The Office Action states on page 5 that Yamaoka does not teach wherein said cut portion further comprises a chemically etched portion.

Yamada teaches mounting a semiconductor and producing a resin-sealed semiconductor device (abstract). Yamada does not teach or suggest, *inter alia*, "a semiconductor structure comprising a substrate having an upper surface and a lower surface, one of said upper surface and said lower surface including at least one groove capable of being broken to separate the substrate into a plurality of segments," as claimed. Because neither Yamaoka or Yamada, alone or in combination, teach or suggest the claimed invention, Applicants respectfully request withdrawal of the rejection.

Claim 16 stands rejected under 35 U.S.C. § 103(a) as being unpatentable over Yamaoka in view of Wakashima et al. (U.S. Patent No. 6,492,203) (hereinafter Wakashima). The Office Action states on page 5 that Yamaoka does not teach wherein said cut portion further comprises a milled portion.

Wakashima teaches semiconductor device fabrication comprising an encapsulation process (abstract). Wakashima does not teach or suggest, *inter alia*, "a semiconductor structure comprising a substrate having an upper surface and a lower surface, one of said upper surface and said lower surface including at least one groove capable of being broken to separate the substrate into a plurality of segments," as claimed. Because neither Yamaoka or Wakashima, whether taken alone or in combination, teach or suggest the claimed invention, Applicants respectfully request withdrawal of the rejection.

In view of the above, each of the presently pending claims in this application is believed to be in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to pass this application to issue.

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Respectfully submitted,

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